

## 7-Channel Relay and Inductive Load Sink Driver

Check for Samples: [ULN2003V12](#)

### FEATURES

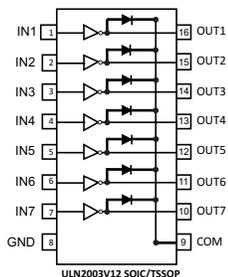
- 7-Channel High Current Sink Drivers
- Supports up to 20V Output Pull-up Voltage
- Supports Wide Range of Low and High Voltage Relays and Inductive Coils
- Low Output VOL of 0.6V (Typical) with
  - 100mA (Typical) Current Sink per Channel at 3.3V Logic Input<sup>(1)</sup>
  - 140mA (Typical) Current Sink per Channel at 5.0V Logic Input<sup>(1)</sup>
- Compatible to 3.3V and 5.0V Micro-controllers and Logic Interface
- Internal Free-wheeling Diodes for Inductive Kick-back Protection
- Input Pull-down Resistors Allows Tri-stating the Input Driver
- Input RC-Snubber to Eliminate Spurious Operation in Noisy Environment
- Low Input and Output Leakage Currents
- Easy to use Parallel Interface
- ESD Protection Exceeds JESD 22
  - 2kV HBM, 500V CDM
- Available in 16-pin SOIC and TSSOP Packages

<sup>(1)</sup> Total current sink may be limited by the internal junction temperature, absolute maximum current levels etc - refer to the Electrical Specifications section for details.

### APPLICATIONS

- Relay and Inductive Load Driver in Various Telecom, Consumer, and Industrial Applications
- Lamp and LED Displays
- Logic Level Shifter

### Functional Diagram



### DESCRIPTION

The ULN2003V12 is a low power upgrade of TI's popular ULN2003 family of 7-channel Darlington transistor array. The ULN2003V12 sink driver features 7 low output impedance drivers that minimize on-chip power dissipation. When driving a typical 12V relay coil a ULN2003V12 will dissipate up to 12 times lower power than an equivalent ULN2003A. The ULN2003V12 driver is pin-to-pin compatible with ULN2003 family of devices in similar packages.

The ULN2003V12 supports 3.3V to 5V CMOS logic input interface thus making it compatible to a wide range of micro-controllers and other logic interfaces. The ULN2003V12 features an improved input interface that minimizes the input DC current drawn from the external drivers. The ULN2003V12 features an input RC snubber that greatly improves its performance in noisy operating conditions. The ULN2003V12 channel inputs feature an internal input pull-down resistor thus allowing input logic to be tri-stated. The ULN2003V12 also supports other logic input levels, e.g. TTL and 1.8V; see typical characteristics section for details.

As shown in the , each output of the ULN2003V12 features an internal free-wheeling diode connected in a common-cathode configuration at the COM pin.

The ULN2003V12 provides flexibility of increasing current sink capability through combining several adjacent channels in parallel. Under typical conditions the ULN2003V12 can support up to 1.0A of load current when all 7-channels are connected in parallel.

The ULN2003V12 can also be used in a variety of other applications requiring a sink drivers. The ULN2003V12 is available in 16-pin SOIC and 16-pin TSSOP packages.

**Table 1. ULN2003V12 Function Table<sup>(1)</sup>**

INPUT (IN1 – IN7)	OUTPUT (OUT1–OUT7)
L	H <sup>+(2)</sup>
H	L
Z	H <sup>+(2)</sup>

(1) L = Low-level (GND); H= High-level; Z= High-impedance;  
(2) H<sup>+</sup> = Pull-up-level



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### ORDERING INFORMATION<sup>(1)</sup>

T <sub>A</sub>	PART NUMBER	PACKAGE		TOP-SIDE MARKING
–40°C to 85°C	ULN2003V12DR	16-Pin SOIC	Reel of 2500	U2003V12
	ULN2003V12PWR	16-Pin TSSOP	Reel of 2000	U2003V12

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Specified at T<sub>J</sub> = –40°C to 125°C unless otherwise noted.

		VALUE		UNIT
		MIN	MAX	
V <sub>IN</sub>	Pins IN1- IN7 to GND voltage	–0.3	5.5	V
V <sub>OUT</sub>	Pins OUT1 – OUT7 to GND voltage		20	V
V <sub>COM</sub>	Pin COM to GND voltage		20	V
I <sub>GND</sub>	Max GND-pin continuous current (100°C < T <sub>J</sub> < +125°C)		700	mA
	Max GND-pin continuous current (T <sub>J</sub> < +100°C)		1.0	A
P <sub>D</sub>	Total device power dissipation at T <sub>A</sub> = 85°C	16 Pin - SOIC	0.86	W
		16 Pin - TSSOP	0.68	W
ESD	ESD Rating – HBM		2	kV
	ESD Rating – CDM		500	V
T <sub>A</sub>	Operating free-air ambient temperature range	–40	85	°C
T <sub>J</sub>	Operating virtual junction temperature	–55	150	°C
T <sub>stg</sub>	Storage temperature range	–55	150	°C

(1) Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### DISSIPATION RATINGS<sup>(1)(2)</sup>

BOARD	PACKAGE	θ <sub>JC</sub>	θ <sub>JA</sub> <sup>(3)</sup>	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> < 25°C	T <sub>A</sub> = 70°C	T <sub>A</sub> = 85°C
High-K	16-Pin SOIC	46°C/W	75°C/W	13.33 mW/°C	1.66 W	1.06 W	0.86 W
High-K	16-Pin TSSOP	49°C/W	95°C/W	10.44 mW/°C	1.31 W	0.84 W	0.68 W

(1) Maximum dissipation values for retaining device junction temperature of 150°C

(2) Refer to TI's design support web page at [www.ti.com/thermal](http://www.ti.com/thermal) for improving device thermal performance

(3) Operating at the absolute T<sub>J,max</sub> of 150°C can affect reliability– for higher reliability it is recommended to ensure T<sub>J</sub> < 125°C

### RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	TYP	MAX	UNIT
V <sub>OUT</sub>	Channel off-state output pull-up voltage			16	V
V <sub>COM</sub>	COM pin voltage			16	V
I <sub>OUT(ON)</sub>	Per channel continuous sink current		VINx = 3.3V	100 <sup>(1)</sup>	mA
			VINx = 5.0V	140 <sup>(1)</sup>	
T <sub>A</sub>	Operating ambient temperature	–40		85	°C
T <sub>J</sub>	Operating junction temperature	–40		125	°C

(1) 1) Refer to [ABSOLUTE MAXIMUM RATINGS](#) for T<sub>J</sub> dependent absolute maximum GND-pin current

## ELECTRICAL CHARACTERISTICS

Specified over the recommended junction temperature range  $T_J = -40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  unless otherwise noted. Typical values are at  $T_J = 25^{\circ}\text{C}$ .

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>INPUTS IN1 THROUGH IN7 PARAMETERS</b>						
$V_{I(ON)}$	IN1–IN7 logic high input voltage	$V_{pull-up} = 3.3\text{ V}$ , $R_{pull-up} = 1\text{ k}\Omega$ , $I_{OUTX} = 3.2\text{ mA}$	1.65			V
$V_{I(OFF)}$	IN1–IN7 logic low input voltage	$V_{pull-up} = 3.3\text{ V}$ , $R_{pull-up} = 1\text{ k}\Omega$ , ( $I_{OUTX} < 20\text{ }\mu\text{A}$ )			0.6	
$I_{I(ON)}$	IN1–IN7 ON state input current	$V_{pull-up} = 12\text{ V}$ , $V_{INx} = 3.3\text{ V}$		12	25	$\mu\text{A}$
$I_{I(OFF)}$	IN1–IN7 OFF state input leakage	$V_{pull-up} = 12\text{ V}$ , $V_{INx} = 0\text{ V}$			250	nA
<b>OUTPUTS OUT1 THROUGH OUT7 PARAMETERS</b>						
$V_{OL(VCE-SAT)}$	OUT1–OUT7 low-level output voltage	$V_{INX} = 3.3\text{ V}$ , $I_{OUTX} = 20\text{ mA}$		0.12	0.15	V
		$V_{INX} = 3.3\text{ V}$ , $I_{OUTX} = 100\text{ mA}$		0.60	0.75	
		$V_{INX} = 5.0\text{ V}$ , $I_{OUTX} = 20\text{ mA}$		0.09	0.11	
		$V_{INX} = 5.0\text{ V}$ , $I_{OUTX} = 140\text{ mA}$		0.60	0.75	
$I_{OUT(ON)}$	OUT1–OUT7 ON-state continuous current <sup>(1)</sup> <sup>(2)</sup> at $V_{OUTX} = 0.6\text{ V}$	$V_{INX} = 3.3\text{ V}$ , $V_{OUTX} = 0.6\text{ V}$	80	100		mA
		$V_{INX} = 5.0\text{ V}$ , $V_{OUTX} = 0.6\text{ V}$	95	140		
$I_{OUT(OFF)(ICEX)}$	OUT1–OUT7 OFF-state leakage current	$V_{INX} = 0\text{ V}$ , $V_{OUTX} = V_{COM} = 16\text{ V}$		0.5		$\mu\text{A}$
<b>SWITCHING PARAMETERS<sup>(3)(4)</sup></b>						
$t_{PHL}$	OUT1–OUT7 logic high propagation delay	$V_{INX} = 3.3\text{ V}$ , $V_{pull-up} = 12\text{ V}$ , $R_{pull-up} = 1\text{ k}\Omega$		50		ns
$t_{PLH}$	OUT1–OUT7 logic low propagation delay	$V_{INX} = 3.3\text{ V}$ , $V_{pull-up} = 12\text{ V}$ , $R_{pull-up} = 1\text{ k}\Omega$		121		ns
$R_{PD}$	IN1–IN7 input pull-down Resistance		210k	300k	390k	$\Omega$
$\zeta$	IN1–IN7 Input filter time constant			9		ns
$C_{OUT}$	OUT1–OUT7 output capacitance	$V_{INX} = 3.3\text{ V}$ , $V_{OUTX} = 0.4\text{ V}$		15		pF
<b>FREE-WHEELING DIODE PARAMETERS<sup>(5)(4)</sup></b>						
$V_F$	Forward voltage drop	$I_{F-peak} = 140\text{ mA}$ , $V_F = V_{OUTX} - V_{COM}$		1.2		V
$I_{F-peak}$	Diode peak forward current			140		mA

- (1) The typical continuous current rating is limited by  $V_{OL} = 0.6\text{ V}$ . Whereas, absolute maximum operating continuous current may be limited by the Thermal Performance parameters listed in the Dissipation Rating Table and other Reliability parameters listed in the Recommended Operating Conditions Table.
- (2) Refer to the Absolute Maximum Ratings Table for  $T_J$  dependent absolute maximum GND-pin current.
- (3) Rise and Fall propagation delays,  $t_{PHL}$  and  $t_{PLH}$ , are measured between 50% values of the input and the corresponding output signal amplitude transition.
- (4) Guaranteed by design only.
- (5) Not rated for continuous current operation – for higher reliability use an external freewheeling diode for inductive loads resulting in more than specified maximum free-wheeling, diode peak current across various temperature conditions

DEVICE INFORMATION

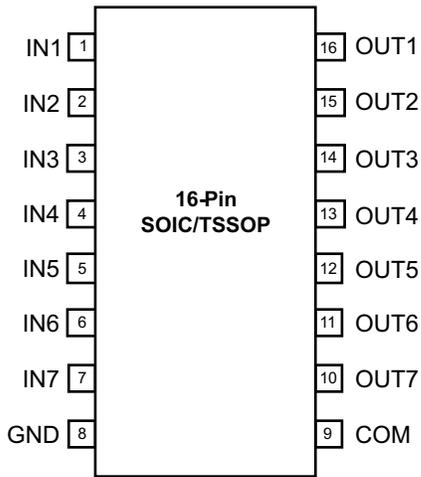


Figure 1. ULN2003V12 PINOUT

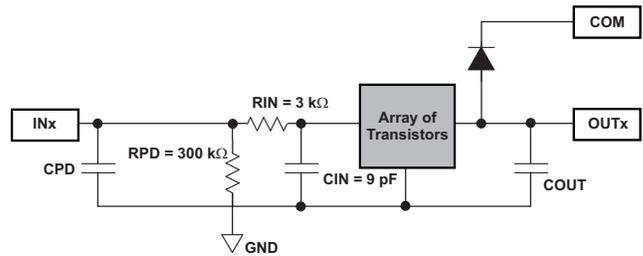


Figure 2. Channel Block Diagram

ULN2003V12 PIN DESCRIPTION

NAME	PIN NUMBER		DESCRIPTION
	16-SOIC	16-TSSOP	
IN1 – IN7	1–7	1–7	Logic Input Pins IN1 through IN7
GND	8	8	Ground Reference Pin
COM	9	9	Internal Free-Wheeling Diode Common Cathode Pin
OUT7 – OUT1	10–16	10–16	Channel Output Pins OUT7 through OUT1

## APPLICATION INFORMATION

### TTL and other Logic Inputs

ULN2003V12 input interface is specified for standard 3V and 5V CMOS logic interface. However, ULN2003V12 input interface may support other logic input levels as well. Refer to [Figure 10](#) and [Figure 11](#) to establish VOL and the corresponding typical load current levels for various input voltage ranges. Application Information section shows an implementation to drive 1.8V relays using ULN2003V12.

### Input RC Snubber

ULN2003V12 features an input RC snubber that helps prevent spurious switching in noisy environment. Connect an external 1kΩ to 5kΩ resistor in series with the input to further enhance ULN2003V12's noise tolerance.

### High-impedance Input Drivers

ULN2003V12 features a 300kΩ input pull-down resistor. The presence of this resistor allows the input drivers to be tri-stated. When a high-impedance driver is connected to a channel input the ULN2003V12 detects the channel input as a low level input and remains in the OFF position. The input RC snubber helps improve noise tolerance when input drivers are in the high-impedance state.

### On-chip Power Dissipation

Use the below equation to calculate ULN2003V12 on-chip power dissipation  $P_D$ :

$$P_D = \sum_{i=1}^N V_{OLi} \times I_{Li}$$

Where:

N is the number of channels active together.

$V_{OLi}$  is the  $OUT_i$  pin voltage for the load current  $I_{Li}$ .

(1)

### Thermal Reliability

It is recommended to limit ULN2003V12 IC's die junction temperature to less than 125°C. The IC junction temperature is directly proportional to the on-chip power dissipation. Use the following equation to calculate the maximum allowable on-chip power dissipation for a target IC junction temperature:

$$PD_{(MAX)} = \frac{(T_{J(MAX)} - T_A)}{\theta_{JA}}$$

Where:

$T_{J(MAX)}$  is the target maximum junction temperature.

$T_A$  is the operating ambient temperature.

$\theta_{JA}$  is the package junction to ambient thermal resistance.

(2)

### Improving Package Thermal Performance

The package  $\theta_{JA}$  value under standard conditions on a High-K board is listed in the [DISSIPATION RATINGS](#).  $\theta_{JA}$  value depends on the PC board layout. An external heat sink and/or a cooling mechanism, like a cold air fan, can help reduce  $\theta_{JA}$  and thus improve device thermal capabilities. Refer to TI's design support web page at [www.ti.com/thermal](http://www.ti.com/thermal) for a general guidance on improving device thermal performance.

## Application Examples

### Inverting Logic Level Shifter

To use ULN2003V12 as an open-collector or an open-drain inverting logic level shifter configure the device as shown in Figure 3. The ULN2003V12's each channel input and output logic levels can also be set independently. When using different channel input and output logic voltages connect the ULN2003V12 COM pin to the maximum voltage.

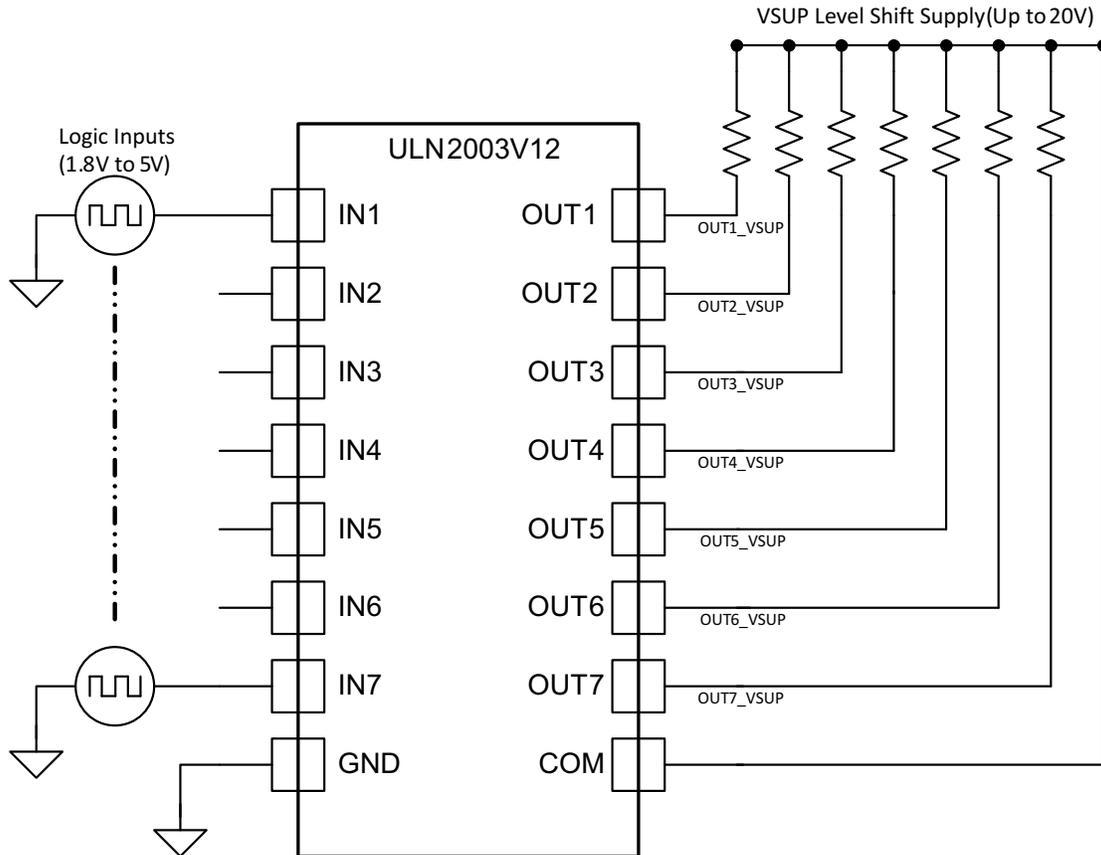
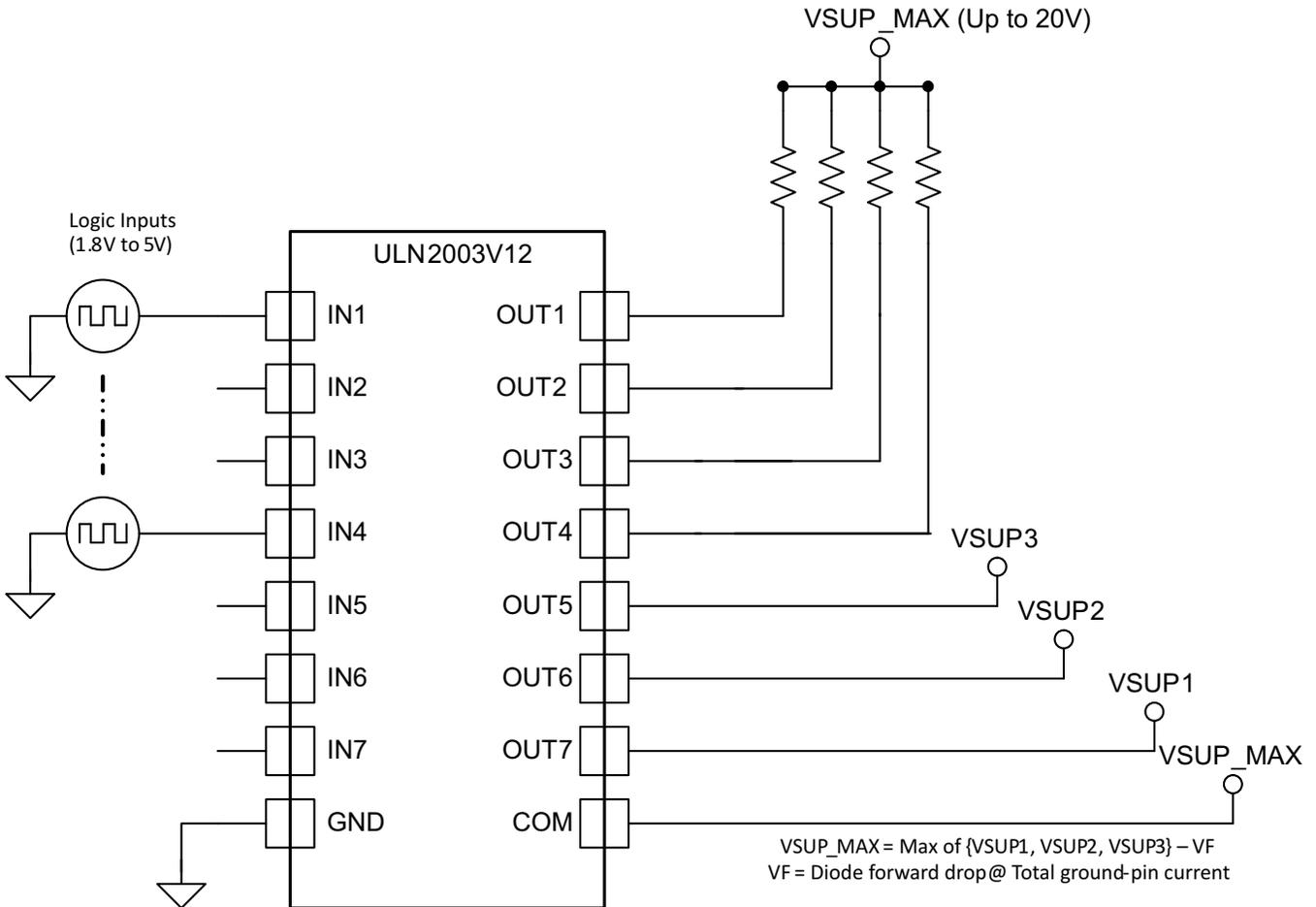


Figure 3. ULN2003V12 as Inverting Logic Level Shifter

**Max Supply Selector**

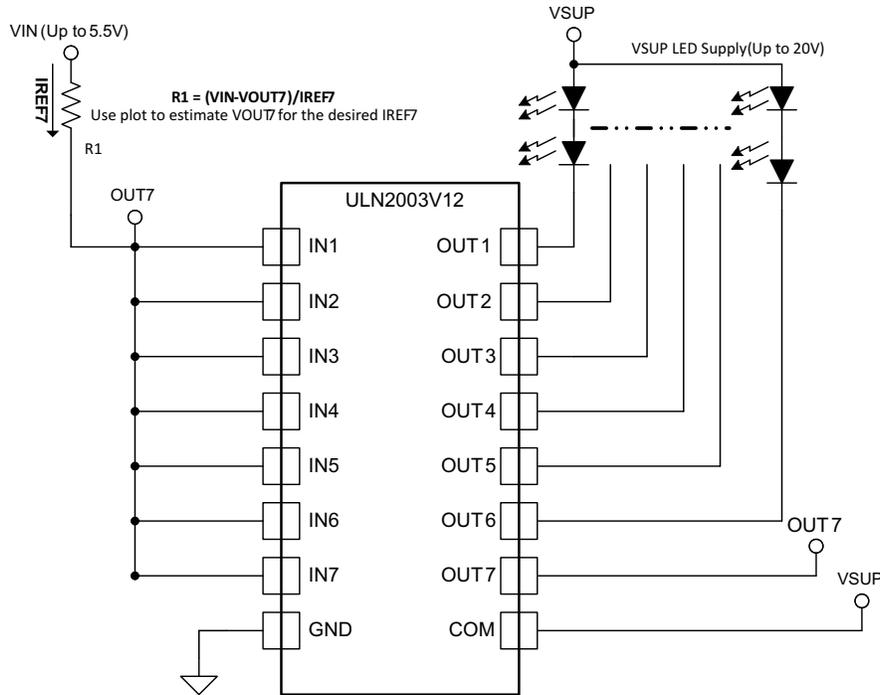
Figure 4 implements a max supply selector along with a 4-channel logic level shifter using a single ULN2003V12. This setup configures ULN2003V12’s channel clamp diodes OUT5 – OUT7 in a diode-OR configuration and thus the maximum supply among VSUP1, VSUP2 and VSUP3 becomes available at the COM pin. The maximum supply is then used as a pull-up voltage for level shifters. Limit the net GND pin current to less than 100mA DC to ensure reliability of the conducting diode. The unconnected inputs IN5-IN7 are pulled to GND potential through 300kΩ internal pull-down resistor.



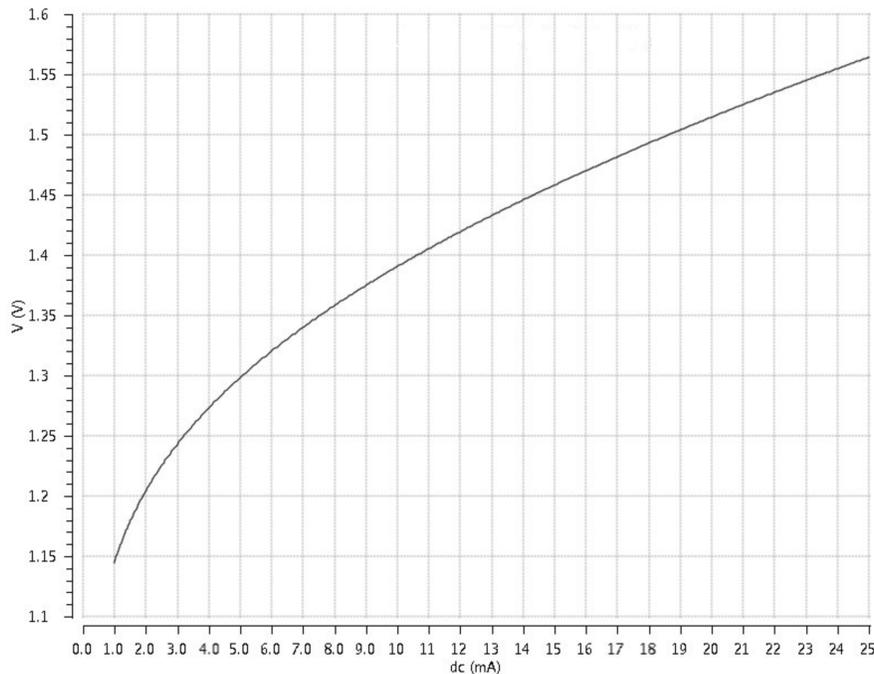
**Figure 4. ULN2003V12 as Max Supply Selector**

**Constant Current Generation**

When configured as per [Figure 5](#) the ULN2003V12 outputs OUT1-OUT6 act as independent constant current sources. The current flowing through the resistor R1 is copied on all other channels. To increase the current sourcing connect several output channels in parallel. To ensure best current copying set voltage drop across connected load such that VOUTx matches to VOUT7.



**Figure 5. ULN2003V12 as a Constant Current Driver**



**Figure 6. ULN2003V12 VOUT vs IREF**

### Unipolar Stepper Motor Driver

Figure 7 shows an implementation of ULN2003V12 for driving a unipolar stepper motor. The unconnected input channels can be used for other functions. When an input pin is left open the internal 300kΩ pull down resistor pulls the respective input pin to GND potential. For higher noise immunity use an external short across an unconnected input and GND pins.

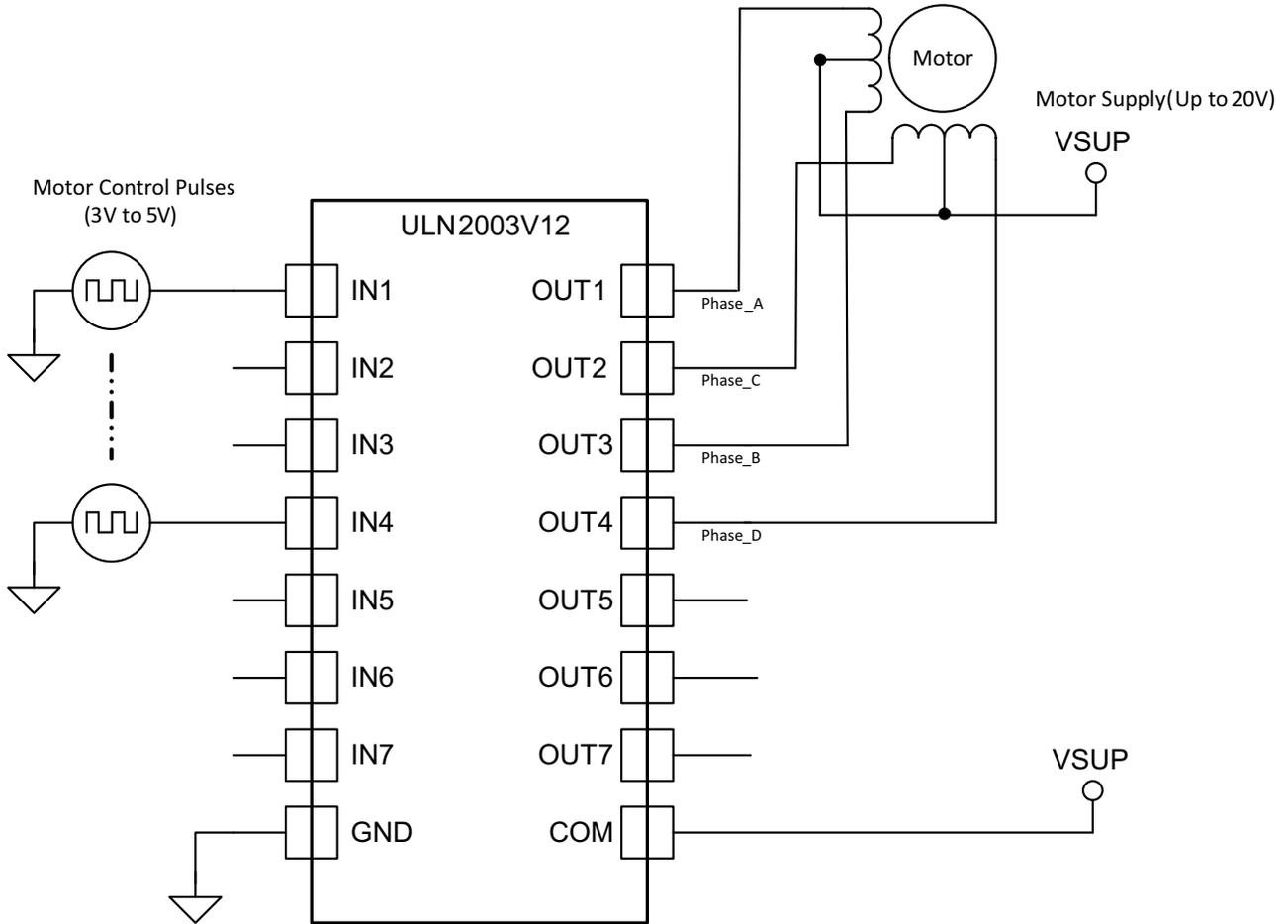
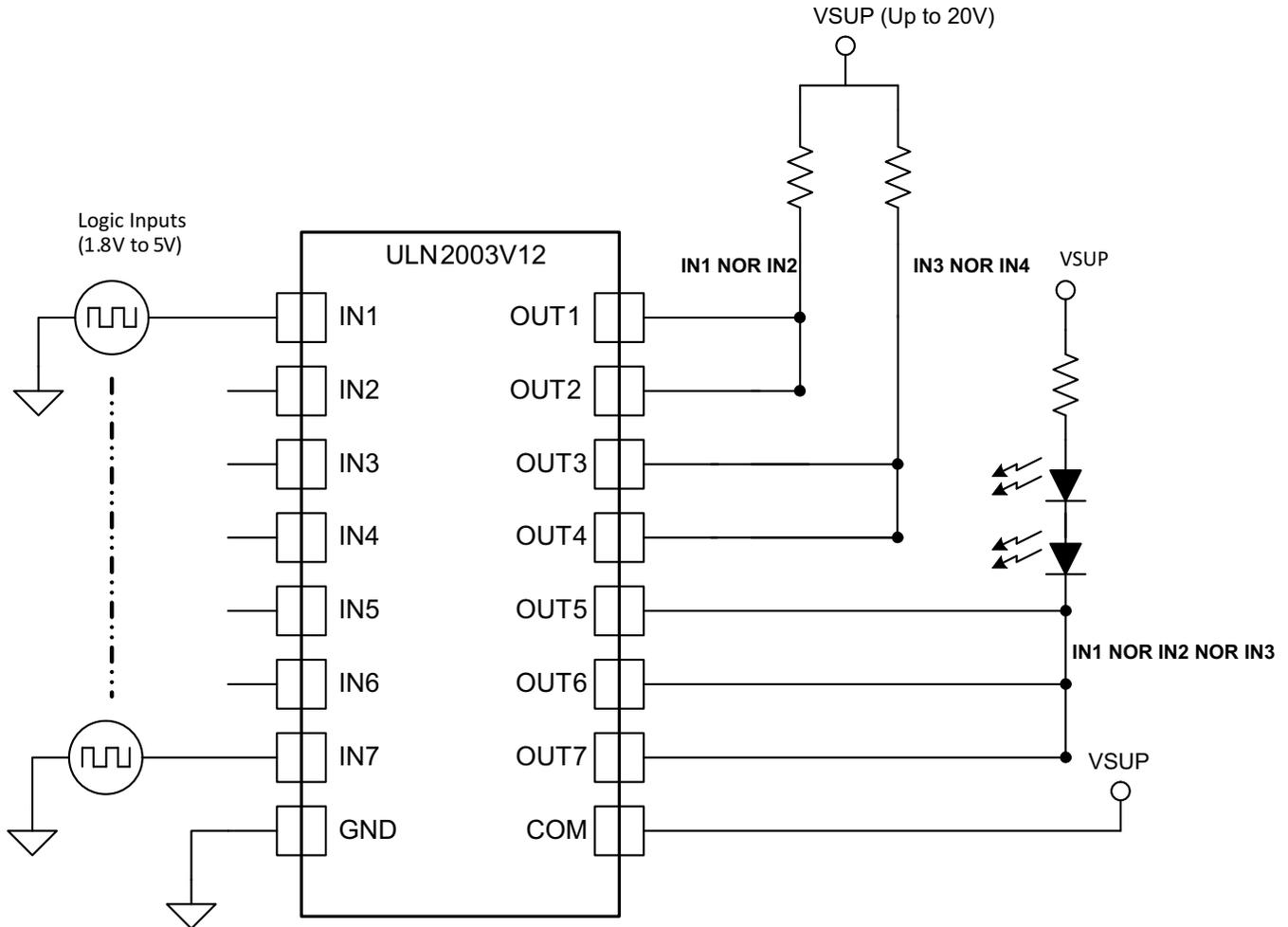


Figure 7. ULN2003V12 as a Stepper Motor Driver

**NOR Logic Driver**

Figure 8 shows a NOR Logic driver implementation using ULN2003V12. The output channels sharing a common pull-up resistor implement a logic NOR of the respective channel inputs. The LEDs connected to outputs OUT5-OUT7 light up when any of the inputs IN5-IN7 is logic-high ( $> V_{IH}$ ).



**Figure 8. ULN2003V12 as a NOR driver**

TYPICAL CHARACTERISTICS

T<sub>A</sub> = +25°C

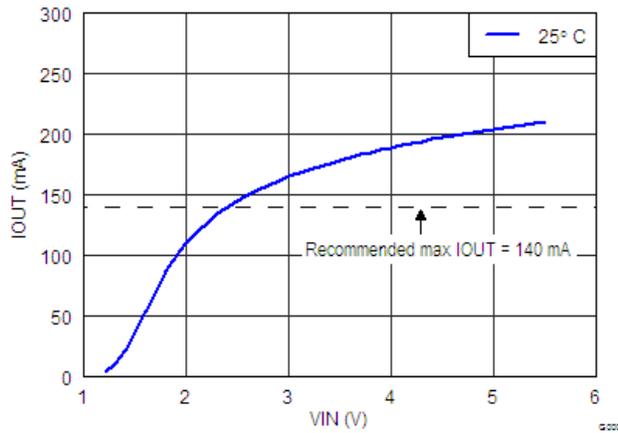


Figure 9. Load Current 1-Channel; VOL=0.6V

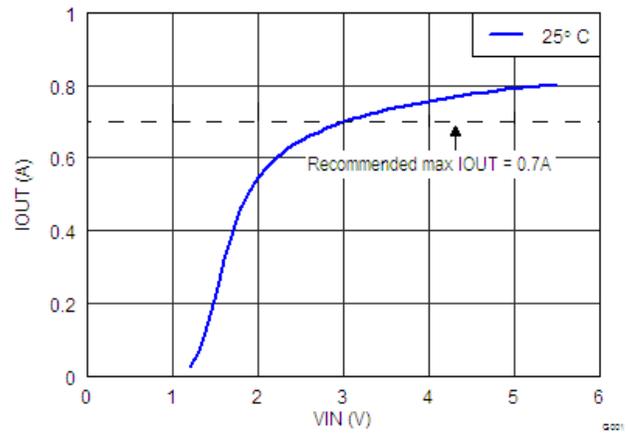


Figure 10. Load Current 7-Channels in parallel; VOL=0.6V

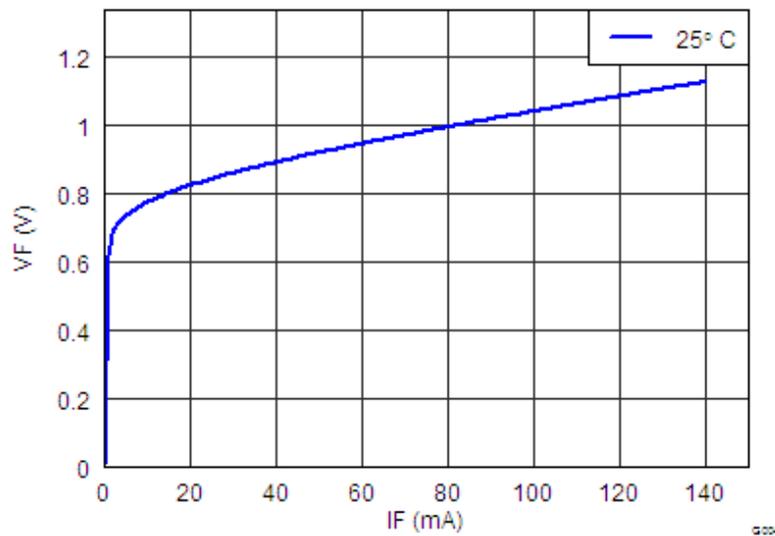


Figure 11. Freewheeling Diode VF versus IF

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
ULN2003V12DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
ULN2003V12PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

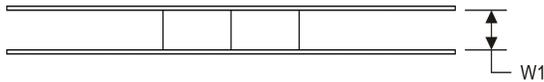
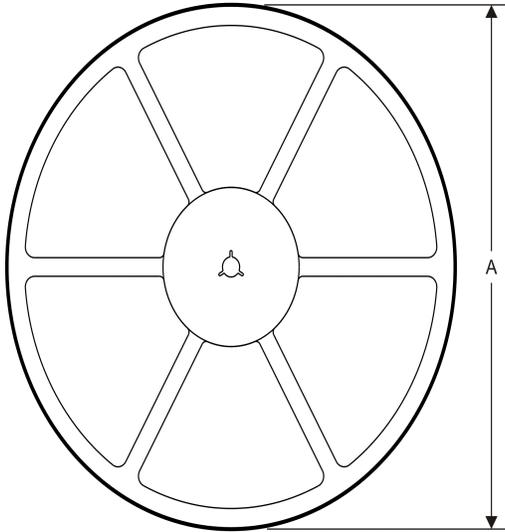
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

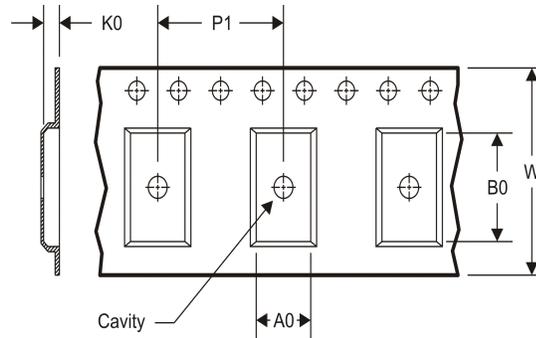
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



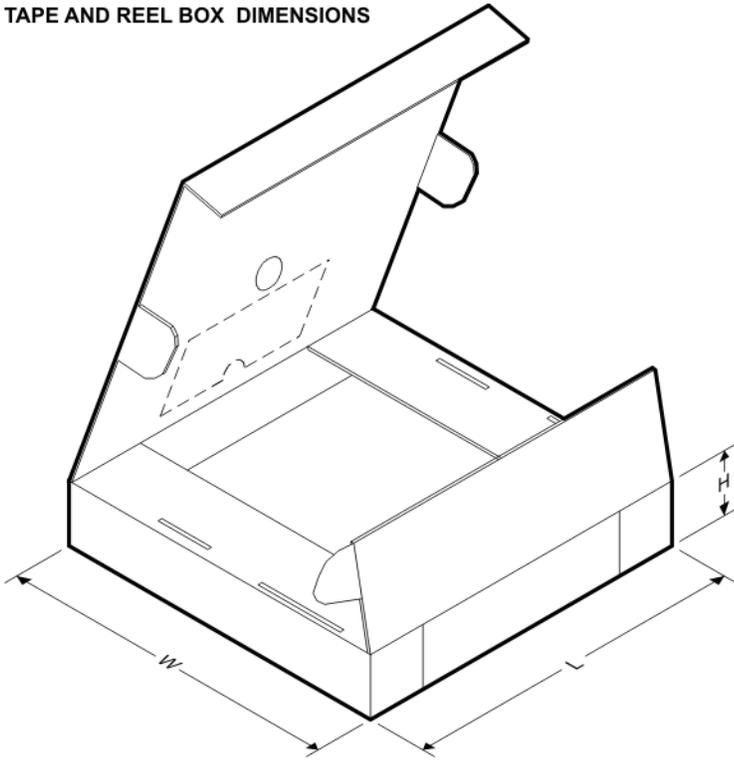
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ULN2003V12PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

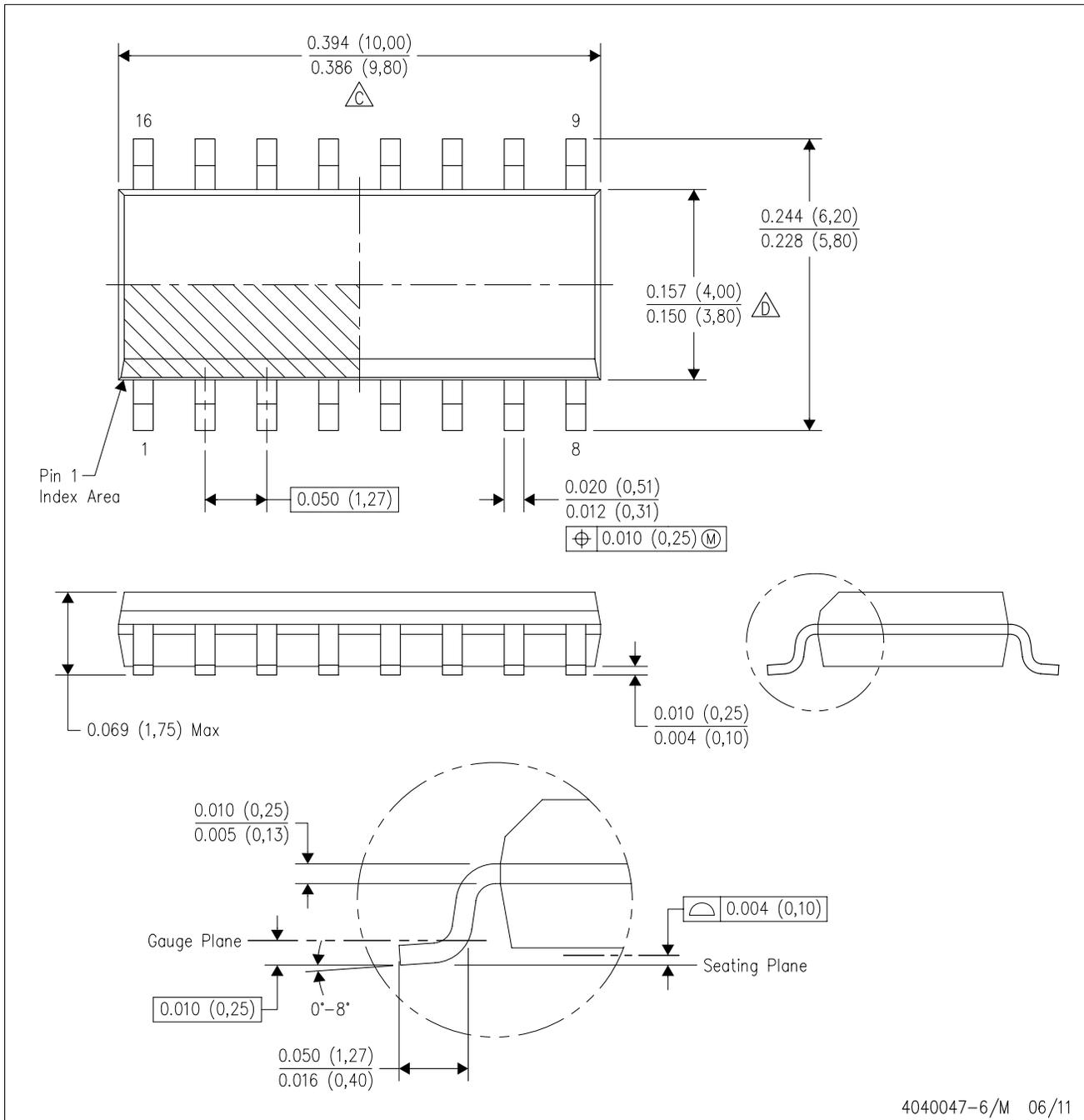


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ULN2003V12PWR	TSSOP	PW	16	2000	364.0	364.0	27.0

D (R-PDSO-G16)

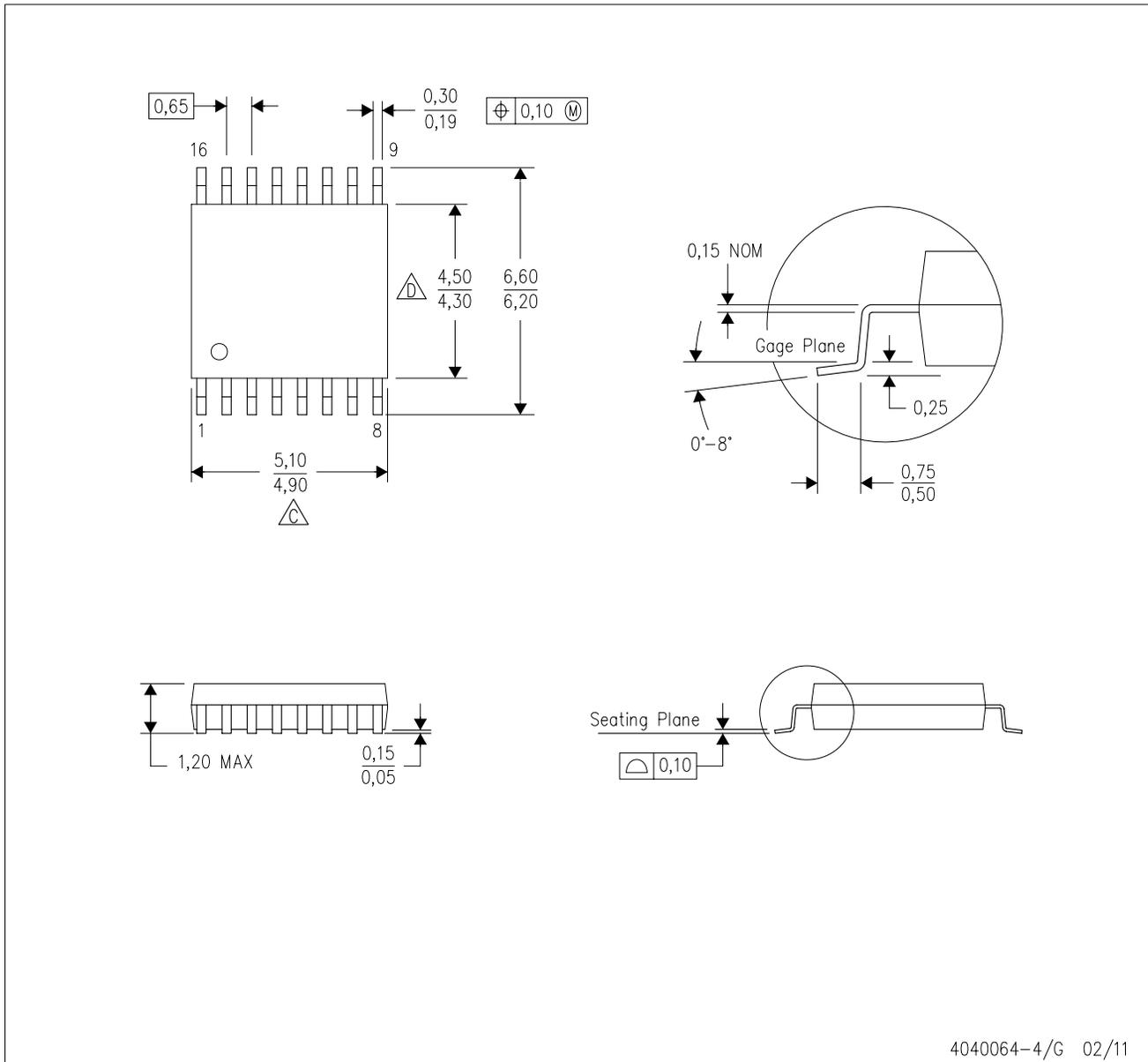
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

PW (R-PDSO-G16)

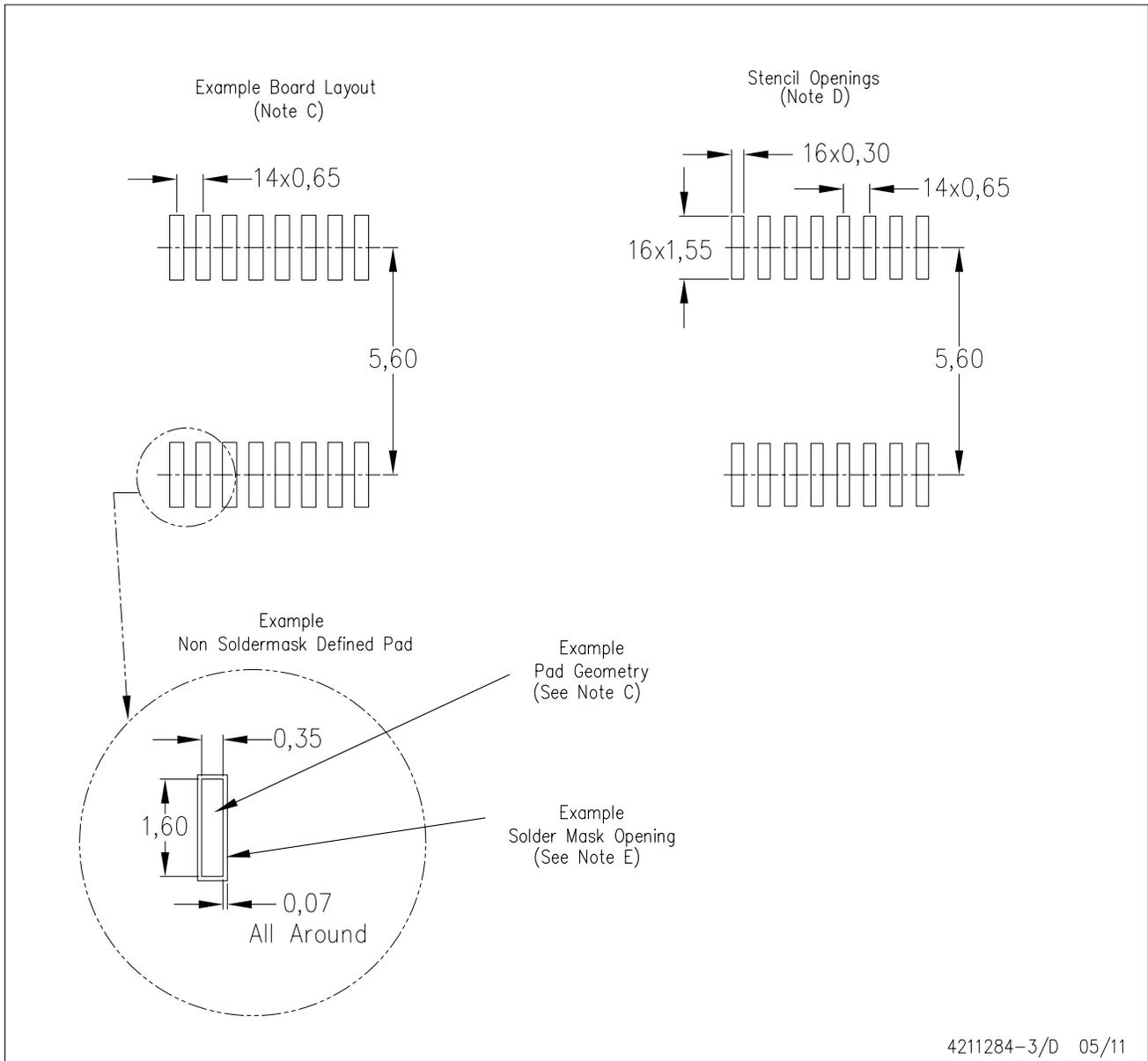
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Mobile Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

TI E2E Community Home Page

[e2e.ti.com](http://e2e.ti.com)

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2012, Texas Instruments Incorporated